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New Series of Horizontal Loading MIL Rugged Rackmount Enclosures By Pixus

Kitchener, Ontario — June 10, 2026 – Pixus Technologies, a provider of embedded computing and chassis solutions, has announced a new MIL rugged 19" rackmount enclosures in a horizontal-loading configuration. The enclosures feature a front-to-rear airflow path.

The new Series of MIL rugged 19" rackmount enclosures come in multiple sizes and configuration options. This includes sizes in 2U, 4U, 5U, 6U, and various depths. The chassis' support Rear Transition Modules (RTMs), with options for deeper sizes for customers to mount other devices. The designs are typically for 3U, 6U, or a hybrid mix of Eurocard sized modules.

Pixus offers these enclosure systems in OpenVPX / SOSA aligned, VME, and customizable form factors. The chassis are designed for MIL– STD-810 for shock/vibration/environmental and MIL-STD-461 for EMI. Various power and I/O options are available.

Pixus offers SOSA aligned backplanes, enclosures, and chassis managers. The company also develops ruggedized and COTS solutions for various VITA and PICMG specifications.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.